

STW60NM50N

N-channel 500 V, 0.035 Ω, 68 A, MDmesh[™] II Power MOSFET in a TO-247 package Datasheet - production data

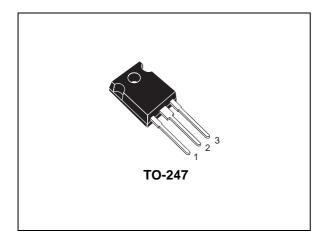
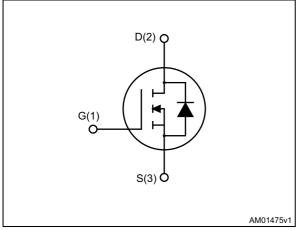


Figure 1. Internal schematic diagram



Features

Order code	V _{DSS} (@T _{jmax})	R _{DS(on) max}	I _D
STW60NM50N	550 V	<0.043 Ω	68 A

- 100% avalanche tested
- Low input capacitance and gate charge
- Low gate input resistance

Applications

• Switching applications

Description

This device is an N-channel Power MOSFET developed using the second generation of MDmesh[™] technology. This revolutionary Power MOSFET associates a vertical structure to the company's strip layout to yield one of the world's lowest on-resistance and gate charge. It is therefore suitable for the most demanding high efficiency converters.

Table 1. Device summary

Order codes	Marking	Packages	Packaging
STW60NM50N	60NM50N	TO-247	Tube

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This is information on a product in full production.

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1 Electrical ratings

Symbol	Parameter	Value	Unit
V _{GS}	Gate- source voltage	±25	V
Ι _D	Drain current (continuous) at $T_C = 25 \text{ °C}$	68	Α
۱ _D	Drain current (continuous) at T _C = 100 °C	43	Α
I _{DM} ⁽¹⁾	Drain current (pulsed)	272	Α
P _{TOT}	Total dissipation at $T_C = 25 \text{ °C}$	446	W
dv/dt (2)	Peak diode recovery voltage slope	15	V/ns
T _{stg}	Storage temperature	-55 to 150	°C
Тj	Max. operating junction temperature	150	°C

Table 2. Absolute maximum ratings

1. Pulse width limited by safe operating area.

2. $I_{SD} \leq ~68$ A, di/dt $\leq ~400$ A/µs, V_{DD} =80% V_{(BR)DSS}

Table 3. Thermal data

Symbol	Parameter	Value	Unit
R _{thj-case}	Thermal resistance junction-case max	0.28	°C/W
R _{thj-amb}	Thermal resistance junction-ambient max	50	°C/W

Table 4. Avalanche characteristics

Symbol	Parameter	Value	Unit
I _{AS}	Avalanche current, repetitive or not-repetitive (pulse width limited by $T_{j \text{ Max}}$)	11	A
E _{AS}	Single pulse avalanche energy (starting Tj=25 °C, I _D =I _{AS} , V _{DD} =50 V)	551	mJ



Electrical characteristics 2

(T_{CASE}=25 °C unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source breakdown voltage	$V_{GS} = 0$, $I_D = 1$ mA	500			V
I _{DSS}	Zero gate voltage drain current	V _{GS} = 0, V _{DS} = 500 V V _{GS} = 0, V _{DS} = 500 V, T _j = 125 °C			1 100	μA
I _{GSS}	Gate-body leakage current	$V_{DS} = 0, V_{GS} = \pm 20 V$			±100	nA
V _{GS(th)}	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	2	3	4	V
R _{DS(on)}	Static drain-source on- resistance	V _{GS} = 10 V, I _D = 34 A		0.035	0.043	Ω

Table 5. On/off state

Table 6. Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
C _{iss}	Input capacitance		-	5790	-	pF
C _{oss}	Output capacitance	V _{DS} = 100 V, f = 1 MHz,	-	365	-	pF
C _{rss}	Reverse transfer capacitance	$V_{GS} = 0$	-	14	-	pF
C _{oss eq.} ⁽¹⁾	Equivalent output capacitance	$V_{GS} = 0$ V, $V_{DS} = 0$ V to 480 V	-	1008	-	pF
Qg	Total gate charge	V _{DD} = 480 V, I _D = 68 A,	-	178	-	nC
Q _{gs}	Gate-source charge	V _{GS} = 10 V (see Figure 14)	-	28	-	nC
Q _{gd}	Gate-drain charge		-	95	-	nC
Rg	Gate input resistance	f=1 MHz gate DC bias=0 Test signal level = 20 mV open drain	-	2	-	Ω

1. $C_{oss eq.}$ is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DS}



Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit		
t _{d(on)}	Turn-on delay time		-	206	-	ns		
t _r	Rise time	$V_{DD} = 300 \text{ V}, \text{ I}_{D} = 32.5 \text{ A}$ R _G = 4.7 Ω V _{GS} = 10 V	-	36	-	ns		
t _{d(off)}	Turn-off delay time	(see Figure 13)	-	40	-	ns		
t _f	Fall time		-	27.5	-	ns		

Table 7. Switching times

Table	8.	Source	drain	diode
	•••		anam	

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I _{SD}	Source-drain current Source-drain current (pulsed)		-		68	A
I _{SDM} ⁽¹⁾	Source-drain current (pulsed)		-		272	А
V _{SD} ⁽²⁾	Forward on voltage	I _{SD} = 68 A, V _{GS} = 0	-		1.6	V
t _{rr}	Reverse recovery time	I _{SD} = 68 A, di/dt = 100 A/µs	-	476		ns
Q _{rr}	Reverse recovery charge	V _{DD} = 100 V	-	10.5		nC
I _{RRM}	Reverse recovery current	(see Figure 15)	-	44		А
t _{rr}	Reverse recovery time	I _{SD} = 68 A, di/dt = 100 A/µs	-	586		ns
Q _{rr}	Reverse recovery charge	V _{DD} = 100 V, T _j = 150 °C	-	15		nC
I _{RRM}	Reverse recovery current	(see Figure 15)	-	51		А

1. Pulse width limited by safe operating area.

2. Pulsed: Pulse duration = $300 \ \mu$ s, duty cycle 1.5%



2.1 Electrical characteristics (curves)

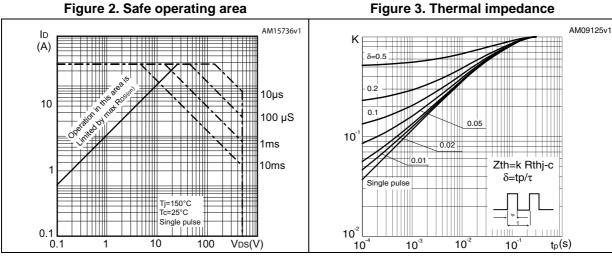


Figure 4. Output characteristics

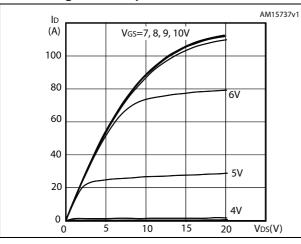


Figure 6. Normalized V_{(BR)DSS} vs temperature

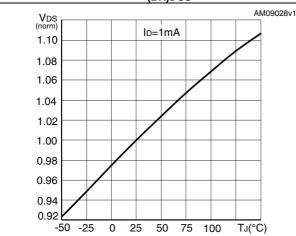


Figure 5. Transfer characteristics

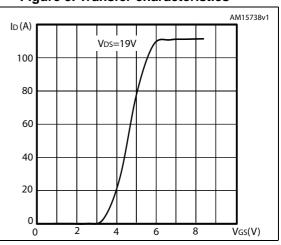
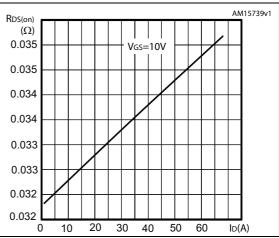
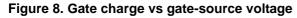
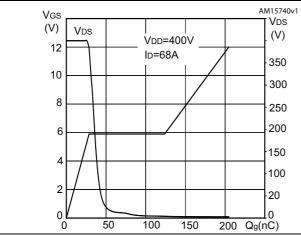


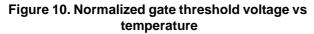
Figure 7. Static drain-source on-resistance











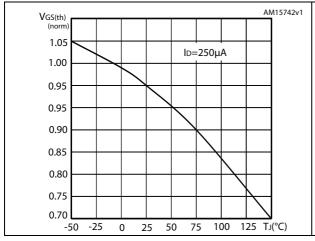


Figure 12. Source-drain diode forward characteristics

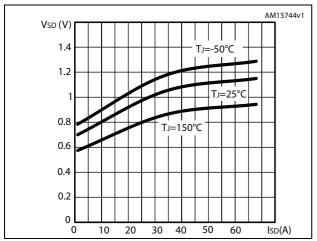


Figure 9. Capacitance variations

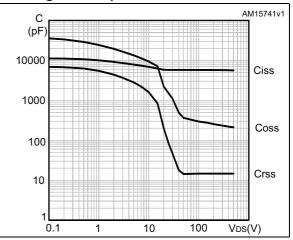
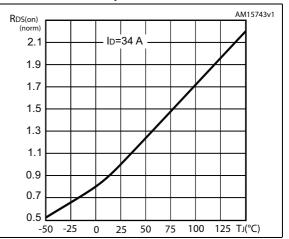


Figure 11. Normalized on-resistance vs temperature





3 Test circuits

Figure 13. Switching times test circuit for resistive load

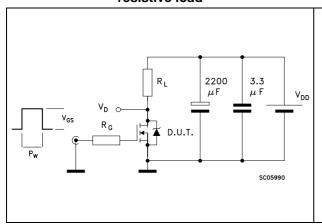


Figure 15. Test circuit for inductive load switching and diode recovery times

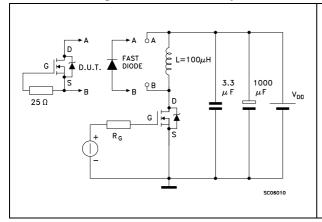
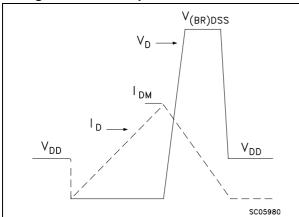
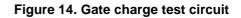
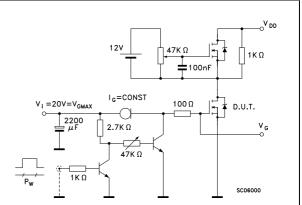


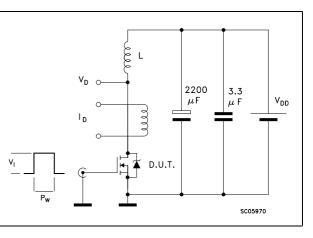
Figure 17. Unclamped inductive waveform



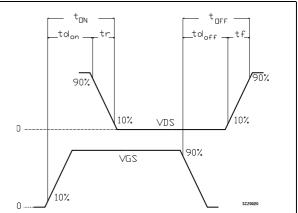














4 Package mechanical data

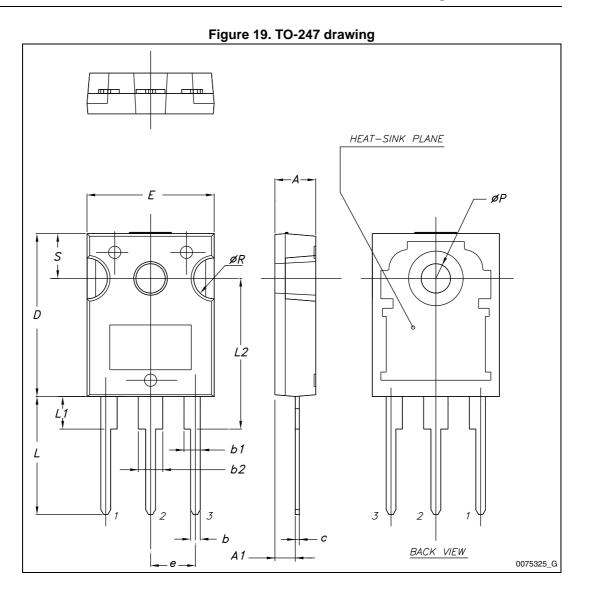
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Dim.	mm.			
	Min.	Тур.	Max.	
А	4.85		5.15	
A1	2.20		2.60	
b	1.0		1.40	
b1	2.0		2.40	
b2	3.0		3.40	
С	0.40		0.80	
D	19.85		20.15	
E	15.45		15.75	
е	5.30	5.45	5.60	
L	14.20		14.80	
L1	3.70		4.30	
L2		18.50		
ØP	3.55		3.65	
ØR	4.50		5.50	
S	5.30	5.50	5.70	

Table 9. TO-247 mechanical data







5 Revision history

Date	Revision	Changes	
26-Apr-2012	1	First release.	
16-Apr-2013	2	 Inserted: Section 2.1: Electrical characteristics (curves) Modified: I_{AS} value on Table 4 Minor text changes 	

Table 10. Document revision history



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